

## Packaging Databases

### Objectives

To realise a series of initial databases to capture information on

- Test Structures for microsystems and microsystems packaging,
- Packaging capabilities
- Packaging solutions

Also to adapt the Materials database to allow it to include data on materials for Microsystems packaging.

The databases are to be constructed taking account of future integration/ inter-linking with WP3 (Reliability) other databases on materials, instrumentation and failure modes for microsystems and microsystems packaging.

### Partners involved

QinetiQ, IMEC, HWU, IMT, IEF and LIRMM

### Summary of results

- Initial test structures database realised by IEF
- QinetiQ to work with IEF and Heriot Watt on databases for Packaging capabilities and Packaging solutions
- IEF and IMT to adapt the Materials database to allow it to include data on materials for Microsystems packaging

### Offer to industry

Depending on results of market survey activities the databases will either be used to underpin some form of commercial offering to industry based on contract consultancy/ research, or industry may be offered direct access to the databases on a commercial basis.

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### Project status

Phase 1 Initial (simple) databases completed and data collection ongoing  
Phase 2 Realisation of suite of databases capable of being interlinked:  
started October 2005